Mar 2021	Photosensors Timeline Estimate	2021	2022	2023	2024
			FY22	FY23	FY24
High-B Sensor Program	Scan of 10-µm XP85122-S, HiCE Planacon				
	Scan of 6-µm Photek MCP PMT, MAPMT253				
	Full-area uniformity scan with UH electronics				
	Incom GEN-III (HRPPD) scan				
MCP-PMT/LAPPD	Beamline test of MCP-PMT/LAPPD with pixel readout				
	mRICH-LAPPD-ToF experiment with Gen-II LAPPD				
	Magnetic field test of LAPPD prototypes				
	Fabrication of 10x10 cm MCP-PMT for prototype validation				
	Bench evaluation of MCP-PMT, LAPPD and HRPPD				
	Integration of UHawaii electronics with available sensors				
	Beamline evaluation of RICH subsystems with available MC	P-PMT/	LAPPD		
SiPM program	Status-of-the-art sensor selection				
	Irradiation and temperature treatment (standard sensors)				
	Post-irradiation response with dedicated readout				
	Custom sensor solutions (with manufacturers)				
	Irradiation and temperature treatment (custom sensors)				
	Engineering of cooling and services				
Sensors and Electronics	collaboration effort within eRD14				
TDR					